

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A printed circuit board comprising:

a core substrate comprising,

a first resin substrate, a second resin substrate having an opening, and a third resin substrate, said first, second, and third resin substrates disposed in a multilayer manner,

while respective interposing bonding plates disposed between the first and second resin substrate and between the second and third resin substrates,

the first resin substrate including a first surface and a second surface opposite to the first surface, and

the opening covered with the second surface of the first resin substrate;
insulating layers and conductive circuit layers alternately laminated on the first surface of the first resin substrate;

a chip capacitor having external capacitor electrodes, the chip capacitor formed in the opening of the second resin substrate;

a first conductive pad formed on the second surface of the first resin substrate facing the chip capacitor and connected to one of the external capacitor electrodes of the chip capacitor via a first conductive adhesive;

a second conductive pad formed on the second surface of the first resin substrate facing the chip capacitor and connected to the other of the external capacitor electrodes of the chip capacitor via a second conductive adhesive;

a first via hole formed in the first resin substrate, the first via hole directly connected to the first conductive pad and a conductive circuit on the core substrate; and

a second via hole formed in the first resin substrate, the second via hole directly connected to the second conductive pad and a conductive circuit on the core substrate.

Claim 2 (Previously Presented): The printed circuit board according to claim 1, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 3 (Previously Presented): The printed circuit board according to claim 1, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 4 (Previously Presented): The printed circuit board according to claim 1, wherein the second resin substrate has a plurality of openings and a plurality of chip capacitors are formed in the openings.

Claim 5 (Previously Presented): The printed circuit board according to claim 1, wherein the conductor circuits are formed on said second resin substrate.

Claims 6-8 (Canceled).

Claim 9 (Previously Presented): The printed circuit board according to claim 1, further comprising:

metal films formed on the external electrodes of said chip capacitor and contacted with the first and second conductive pads, respectively.

Claim 10 (Previously Presented): The printed circuit board according to claim 9, wherein the metal films formed on the external electrodes of said chip capacitor are plated films comprising copper.

Claims 11-14 (Canceled)

Claim 15 (Currently Amended): A printed circuit board constituted by alternately laminating insulating layers and conductive circuits on a core substrate containing a chip

capacitor, which includes a first electrode, a second electrode and a dielectric made of ceramic, wherein

the core substrate containing said chip capacitor comprises a first resin substrate, a second resin substrate having an opening for containing the chip capacitor and a third resin substrate in a multilayer manner while interposing bonding plates,

said first resin substrate including,

at least two conductive pads disposed on a side of the first resin substrate

facing the chip capacitor and connected to two electrodes of the chip capacitor

through a conductive adhesive layer respectively, and

an insulating bonding agent disposed between the at least two conductive pads,

said first resin substrate and said chip capacitor are coupled to each other by ~~an~~ the insulating bonding agent, and a coefficient of thermal expansion of the insulating bonding agent is lower than a coefficient of thermal expansion of said first resin substrate,

~~a conductive pad is formed on the first resin substrate and connected to an electrode of the chip capacitor, and~~

a via hole, through which the at least two conductive pads are is connected to the conductive circuit on the core substrate, is formed in the first resin substrate.

Claims 16-78 (Canceled)

Claim 79 (Previously Presented): The printed circuit board according to claim 15, further comprising:

a metal film formed on the electrode of the chip capacitor.

Claim 80 (Previously Presented): The printed circuit board according to claim 79, wherein the metal film formed on the electrode of the chip capacitor is a plated film comprising copper.

Claim 81(Previously Presented): The printed circuit board according to claim 15, wherein each of said bonding plates has a core impregnated with a thermosetting resin.

Claim 82 (Previously Presented): The printed circuit board according to claim 15, wherein each of said first, second and third resin substrates having a core made of glass cloth and impregnated with a resin.

Claim 83 (Previously Presented): The printed circuit board according to claim 15, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area,

wherein an IC chip is to be mounted on the bump area.

Claim 84 (Currently Amended): The printed circuit board according to claim 1, further comprising a plurality of bumps formed on an outer layer of the insulating layers and constituting a bump area, wherein at least one of the bumps is electrically connected to the electrode of the chip capacitor through a via hole formed immediately below the bump area.

Claim 85 (Previously Presented): The printed circuit board according to claim 84, wherein an IC chip is to be mounted on the bump area.

Claims 86-93 (Canceled).

Claim 94 (New): The printed circuit board according to claim 1, wherein:

the bonding plates are formed of an extrudable compound, and

the chip capacitor is encased in the extrudable compound.

Claim 95 (New): The printed circuit board according to claim 15, wherein:

the bonding plates are formed of an extrudable compound, and

the chip capacitor is encased in the extrudable compound.

Claim 96 (New): The printed circuit board according to claim 1, wherein the first conductive adhesive and the second conductive adhesive are of a same material.

Claim 97 (New): The printed circuit board according to claim 1, further comprising:
insulating layers and conductive circuits alternately laminated on the core substrate.

Claim 98 (New): The printed circuit board according to claim 1, wherein the chip
capacitor comprises a dielectric made of ceraminc.